

FIG.1A

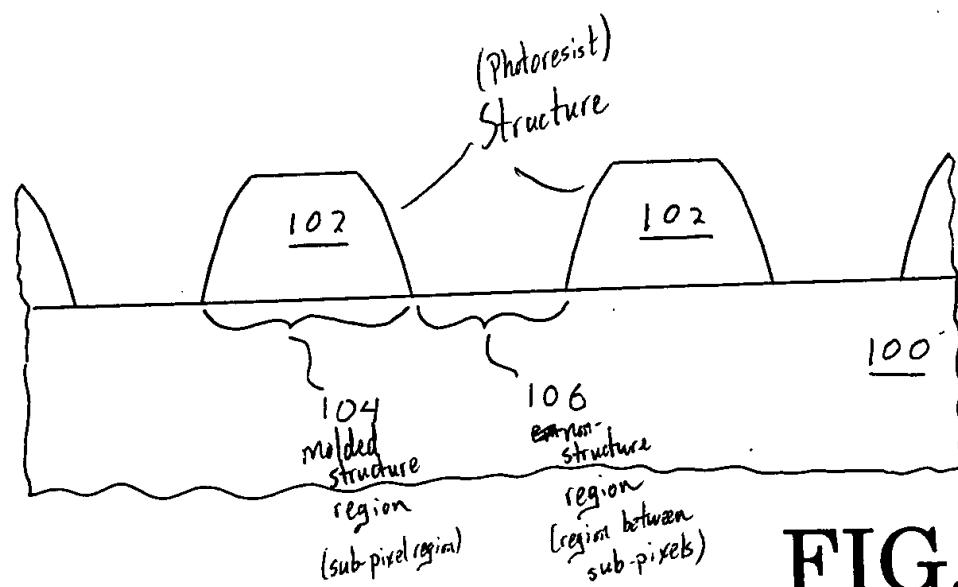
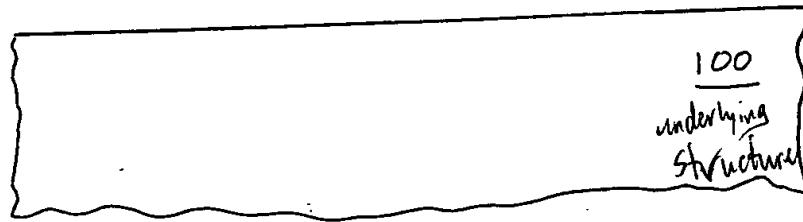


FIG.1B

electroplating
108 seed layer

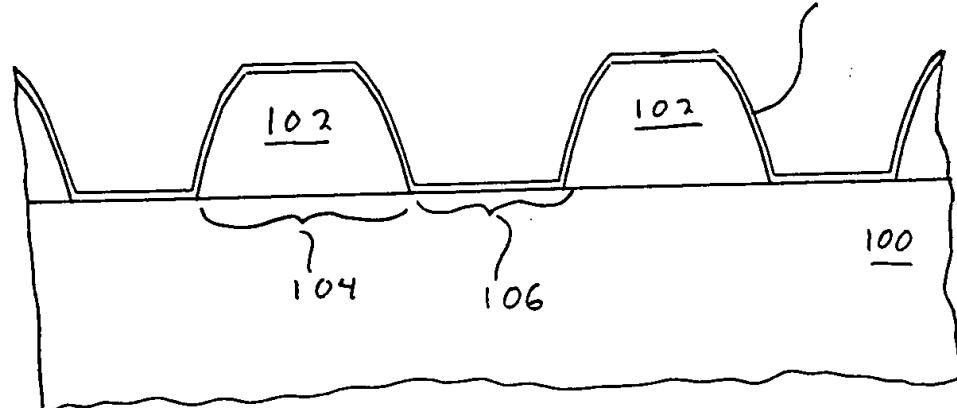


FIG.1C

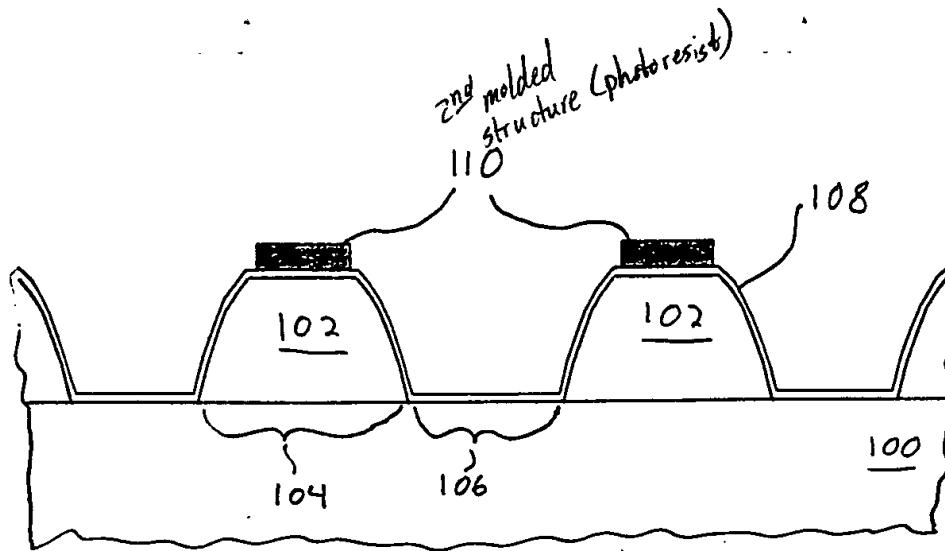


FIG. 1D

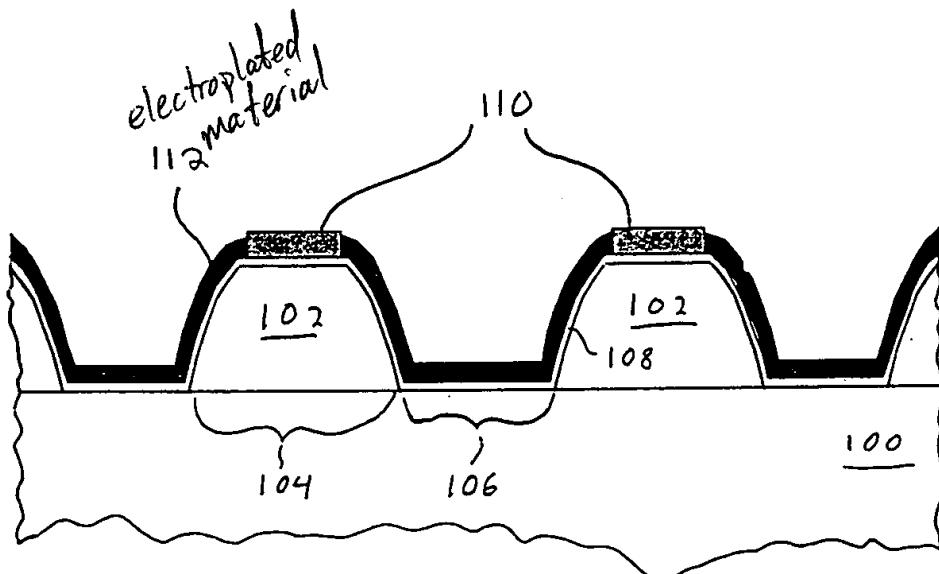


FIG. 1E

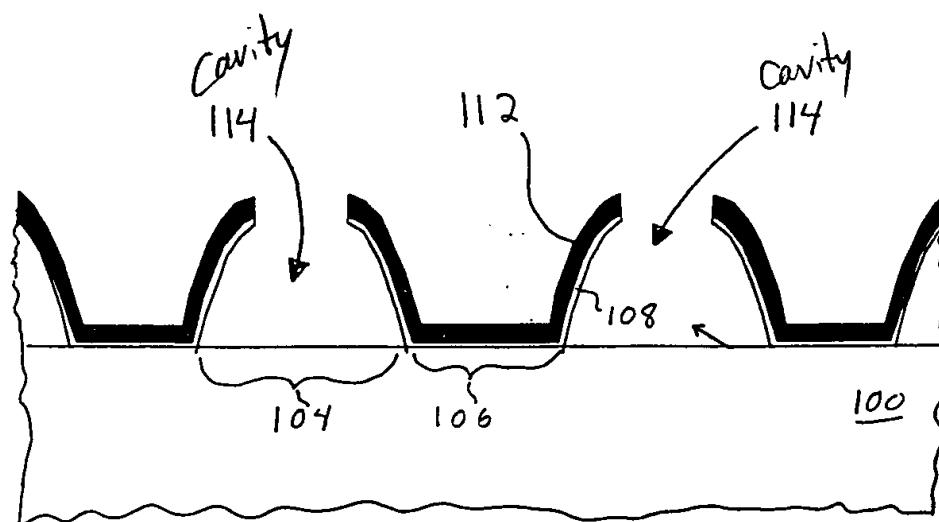


FIG. 1F

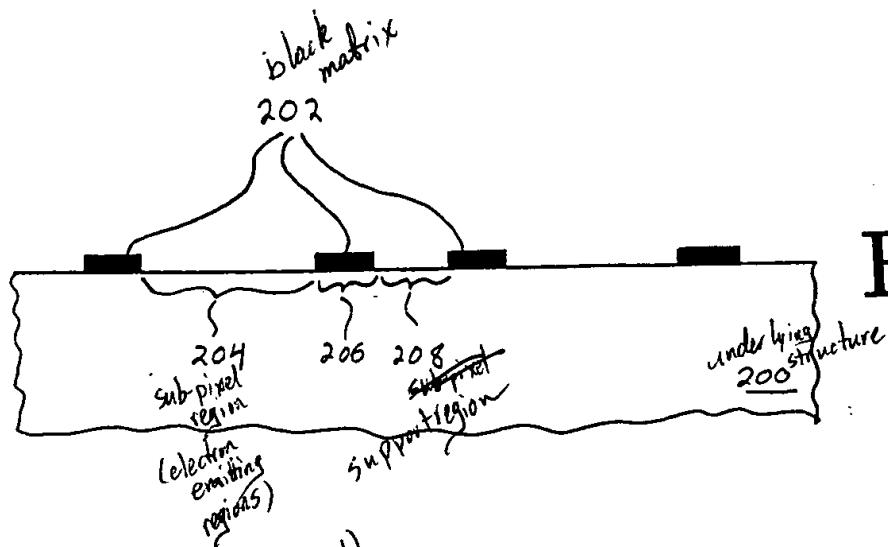


FIG.2A

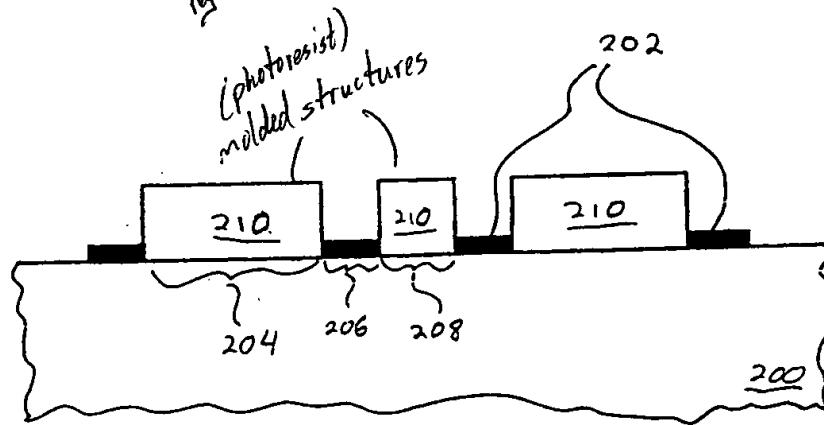


FIG.2B

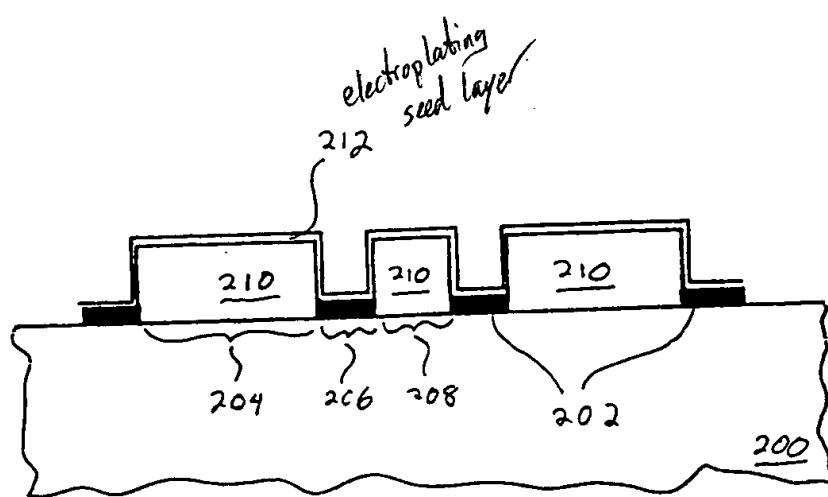


FIG.2C

FIG.2D

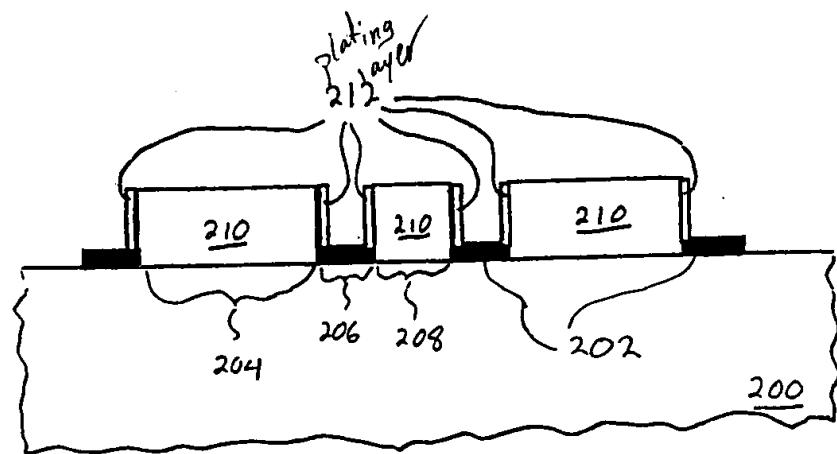


FIG.2E

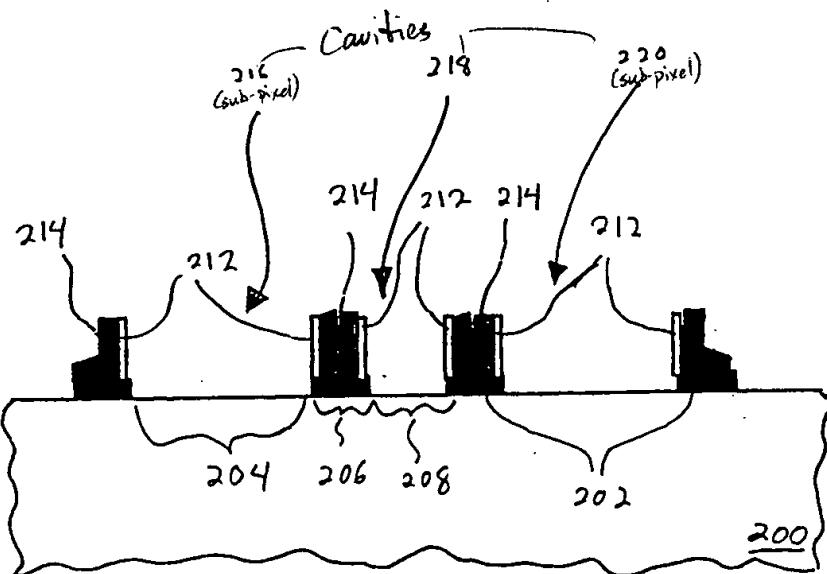
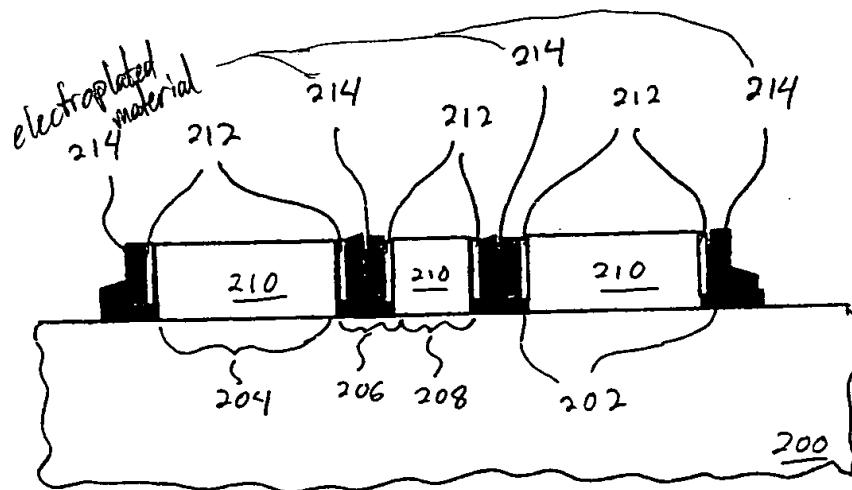
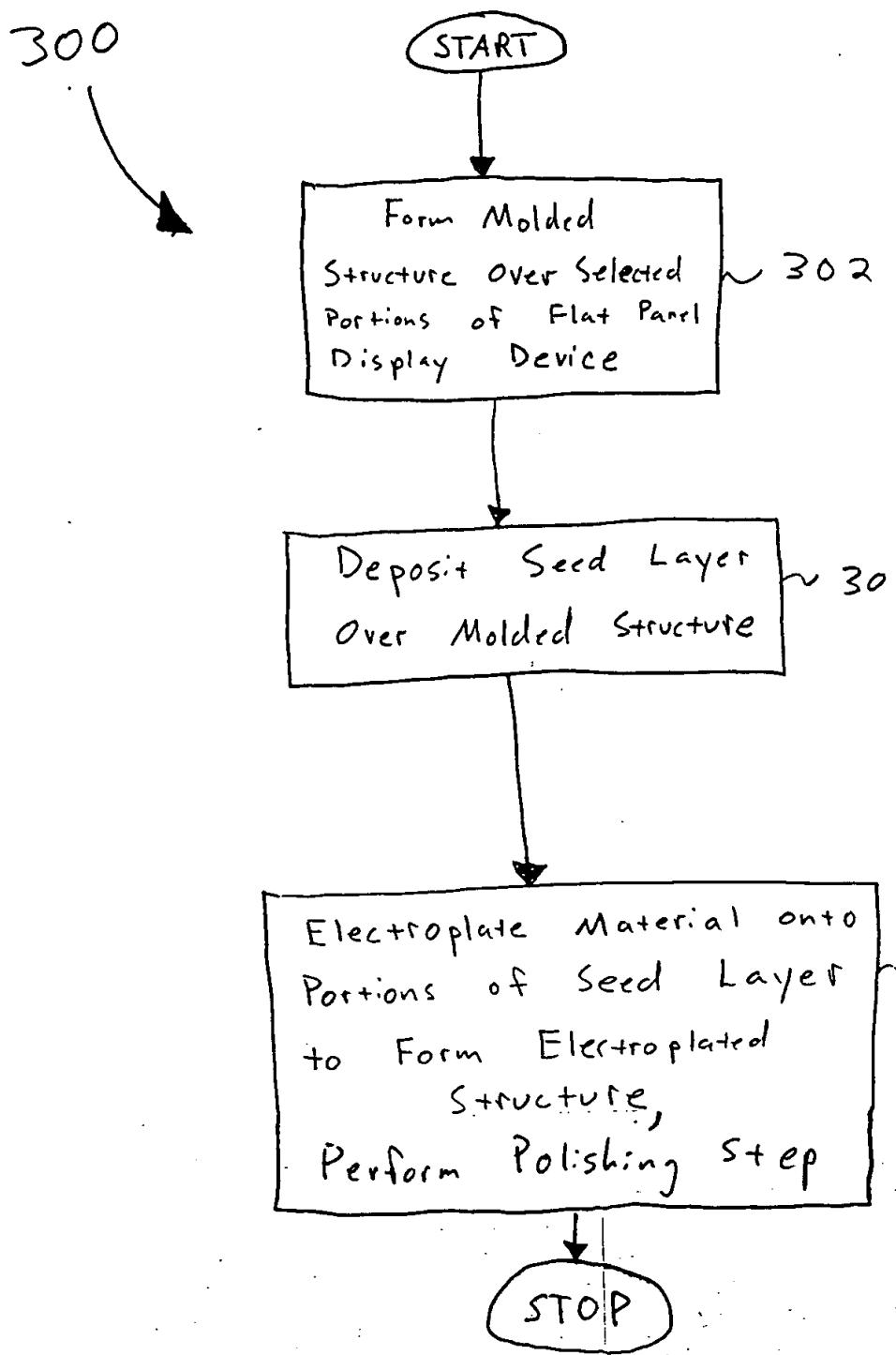


FIG.2F

FIG.3



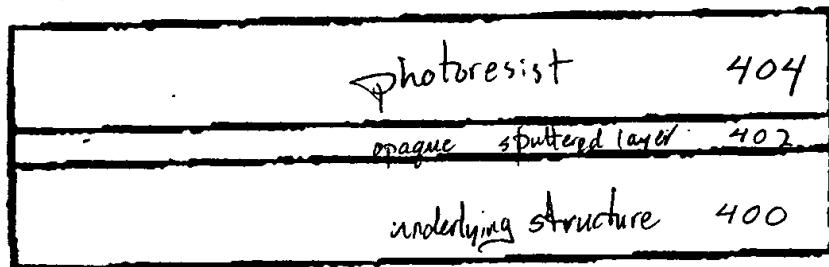
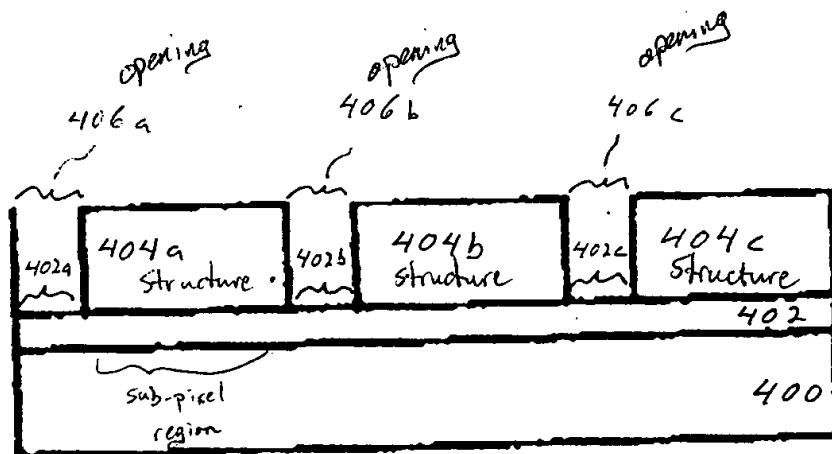


Fig. 4 A



(electron emitting
portions)
Fig. 4 B

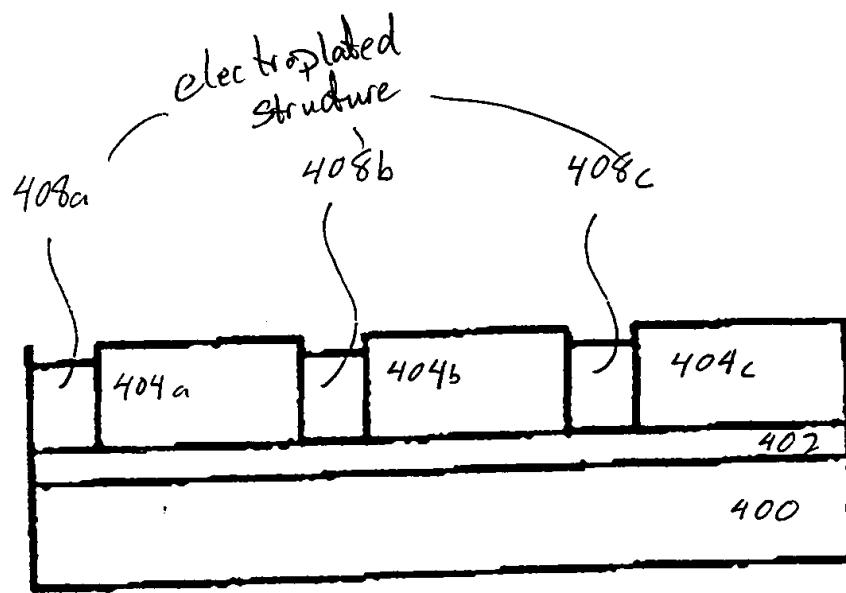


Fig. 4C

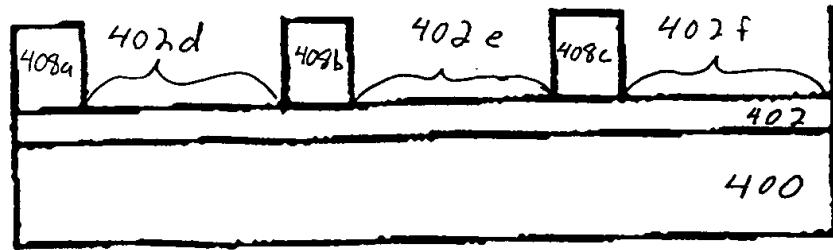


Fig. 4D

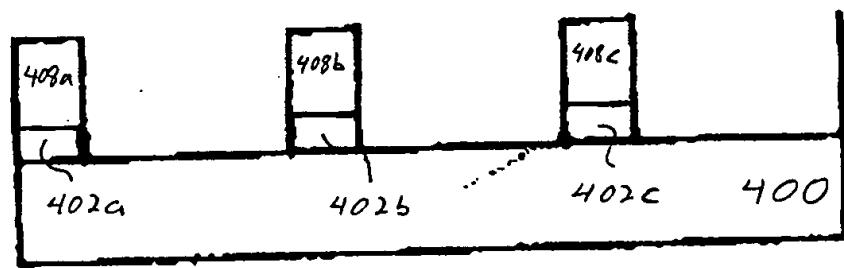


Fig. 4 E

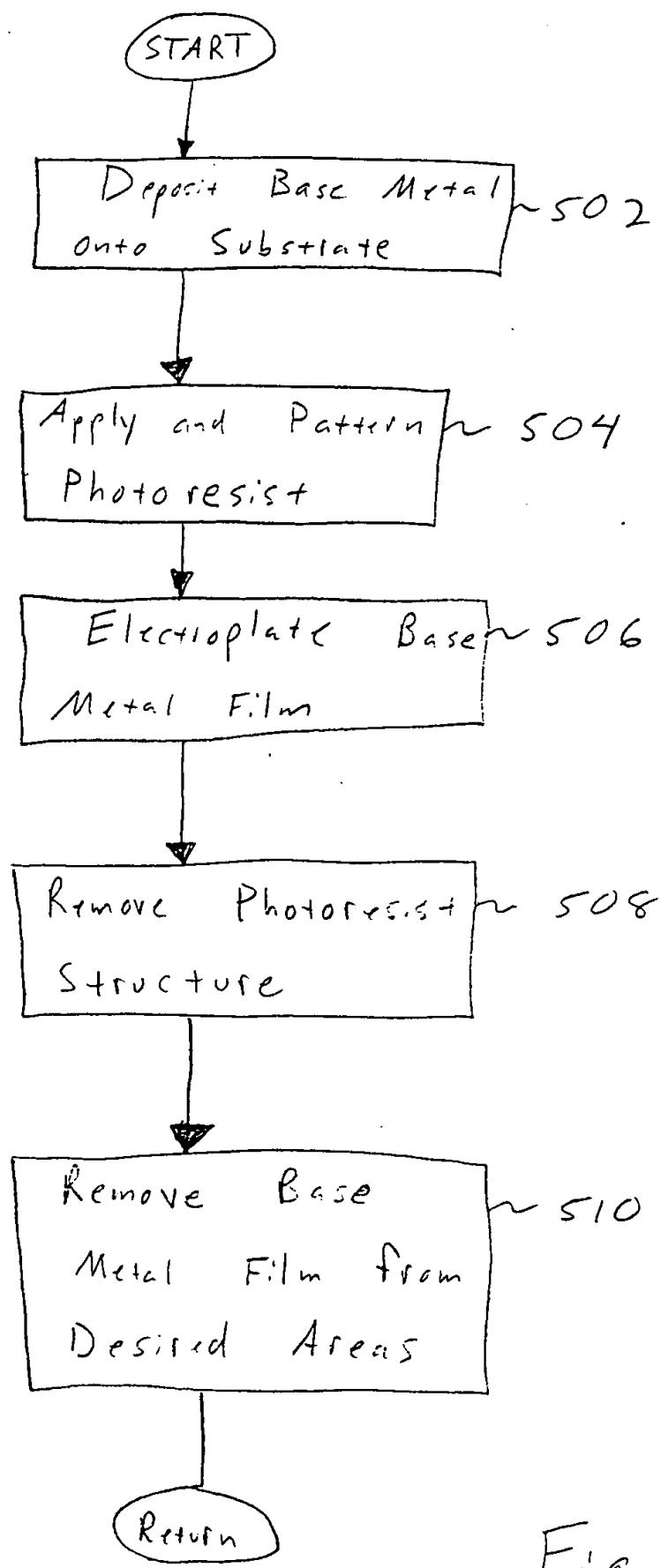


Fig. 5

FIG.1A

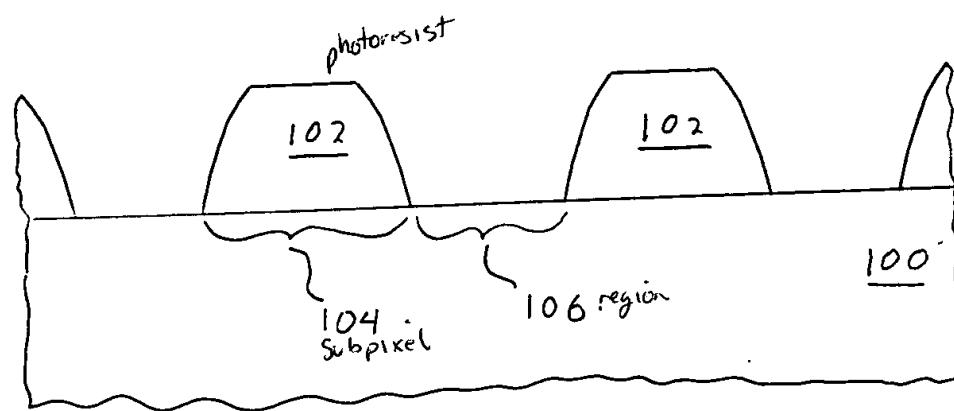
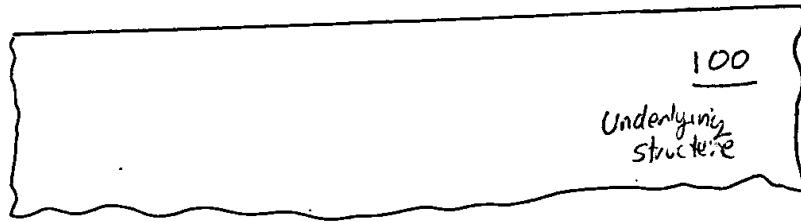


FIG.1B

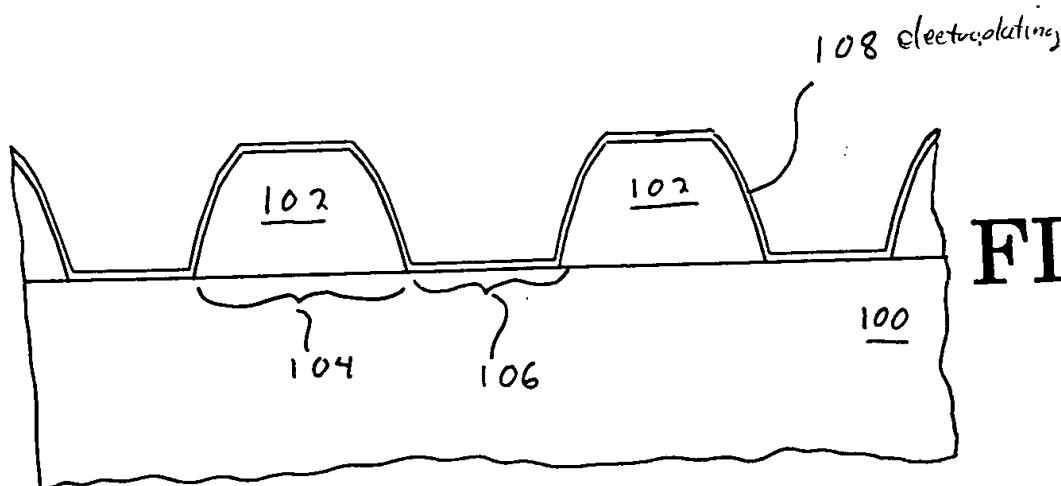
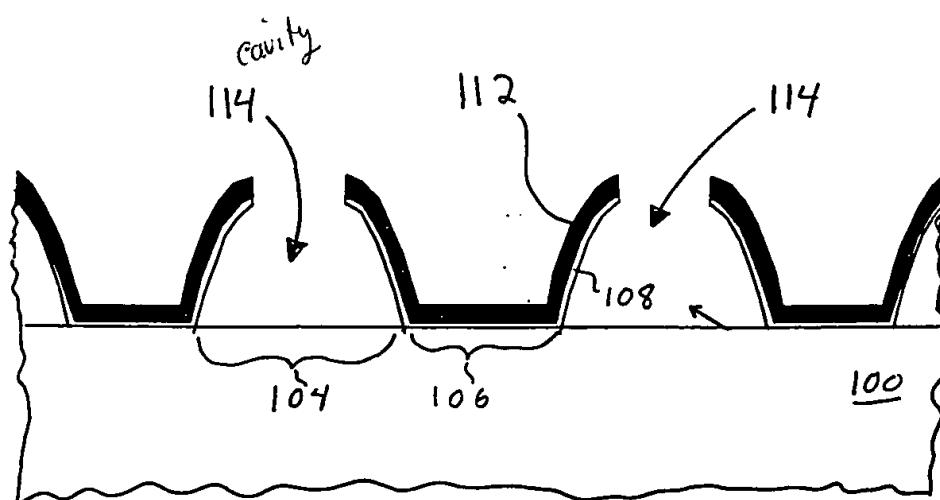
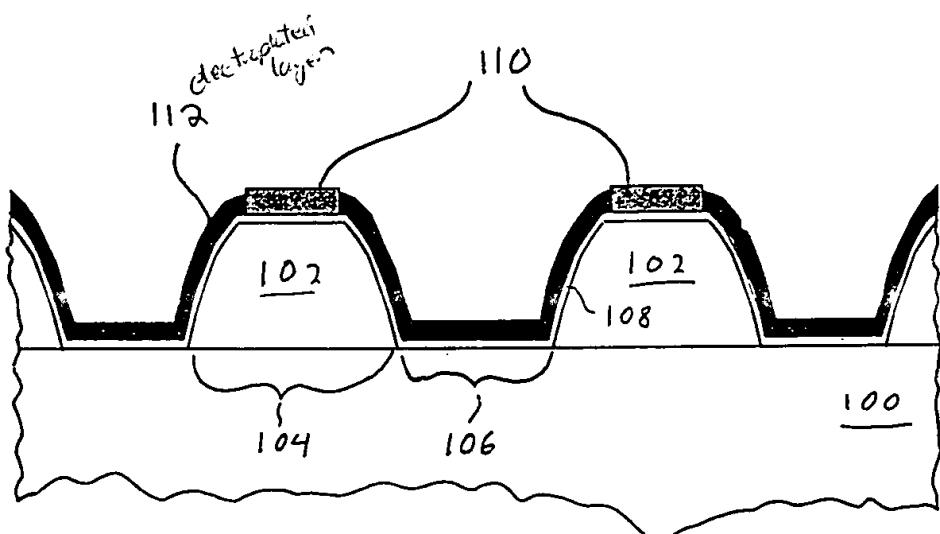
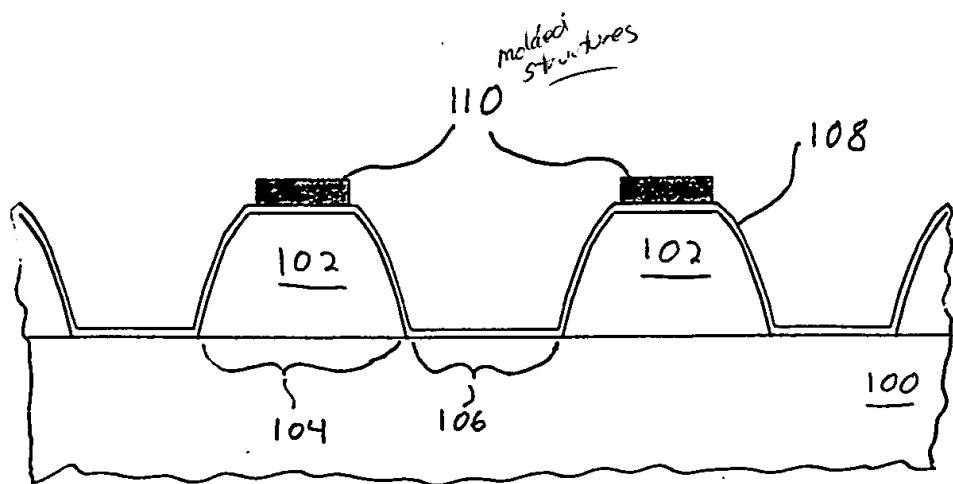


FIG.1C



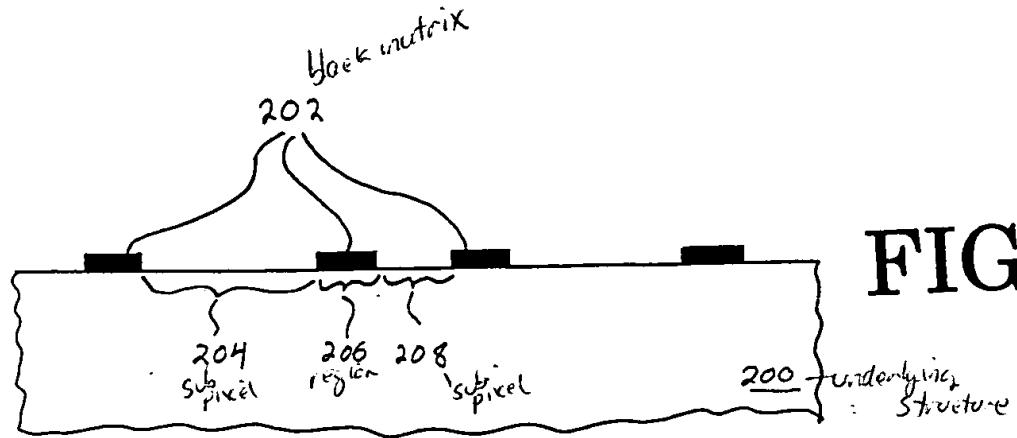


FIG.2A

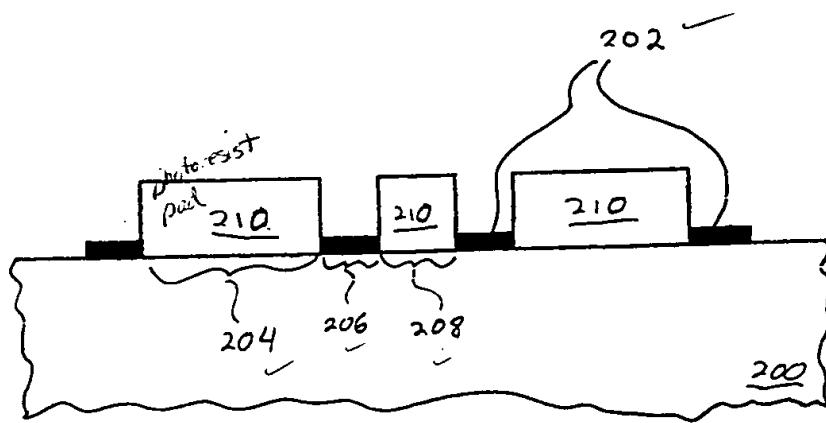


FIG.2B

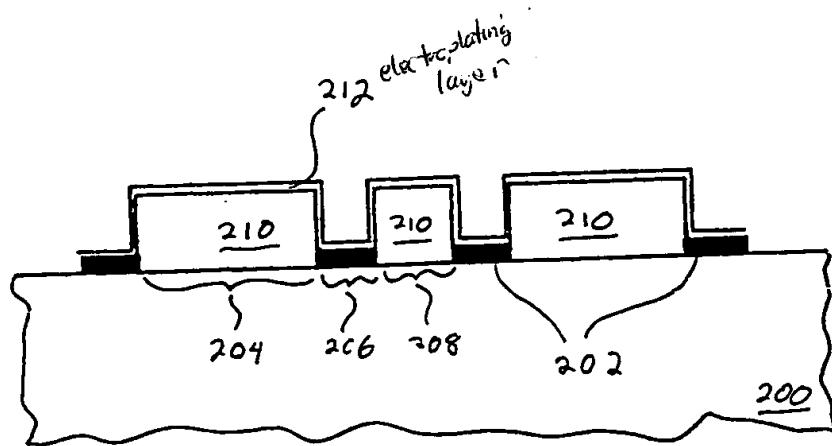


FIG.2C

FIG.2D

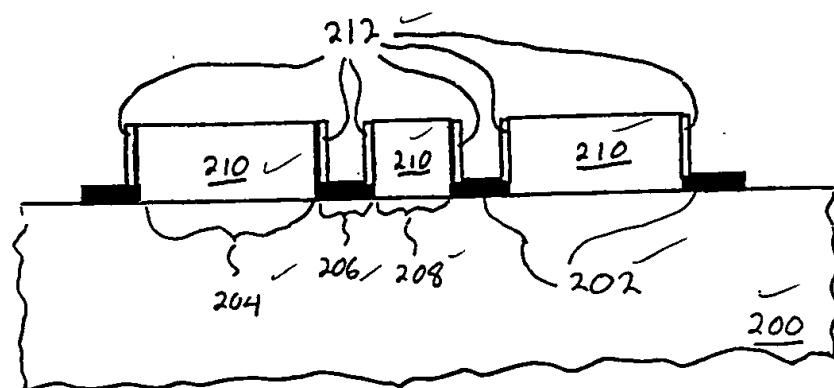


FIG.2E

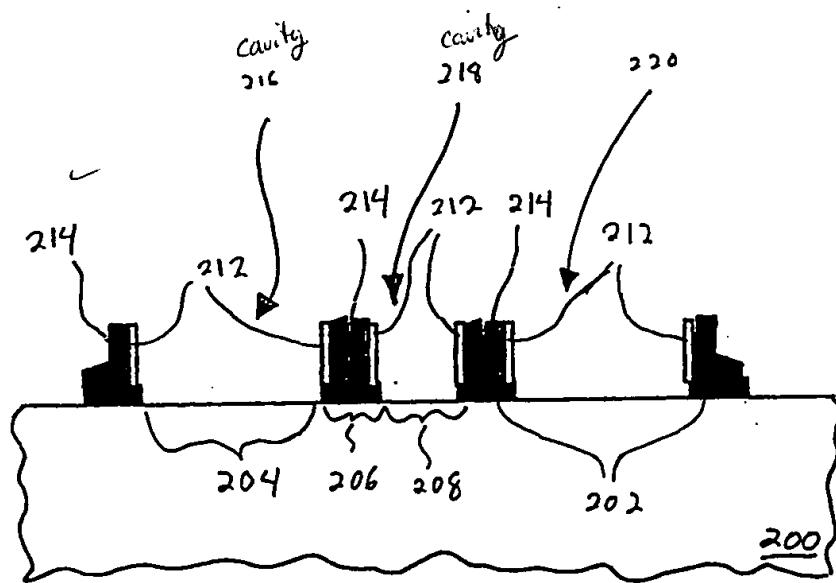
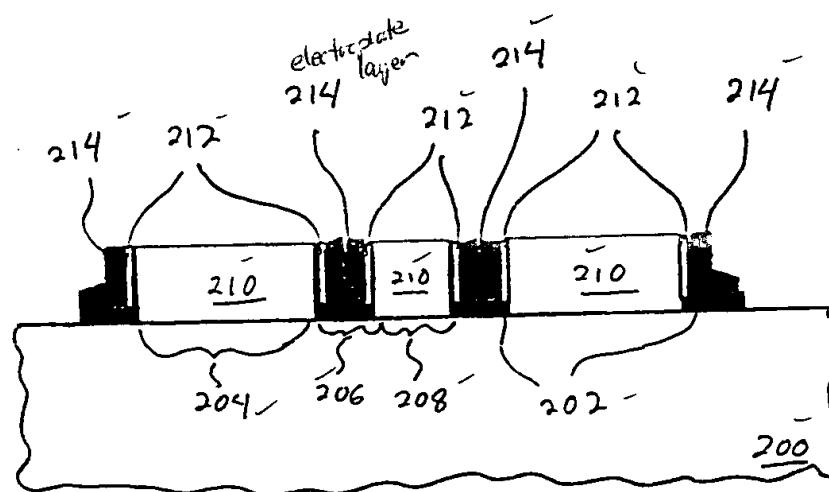
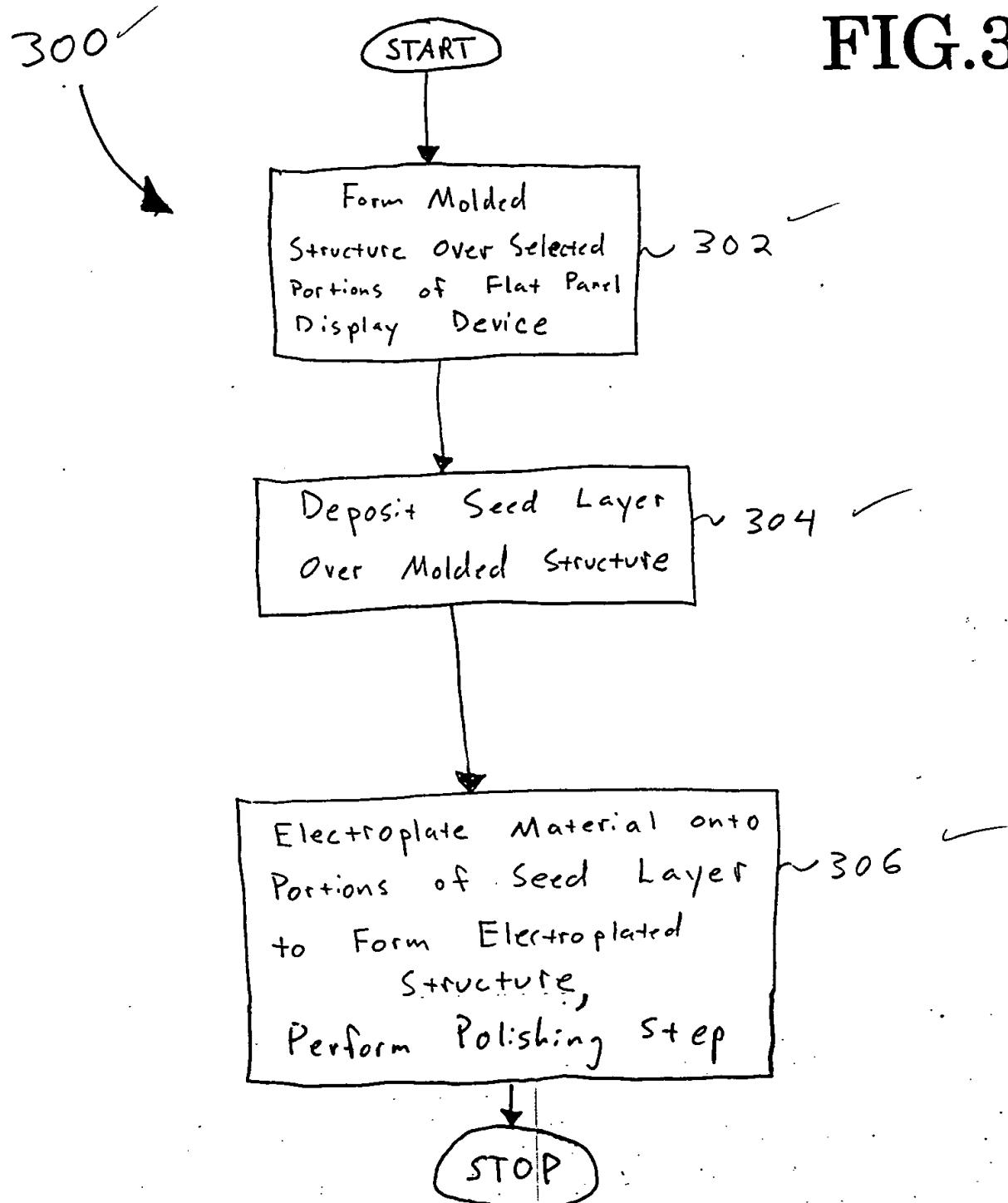


FIG.2F

FIG.3



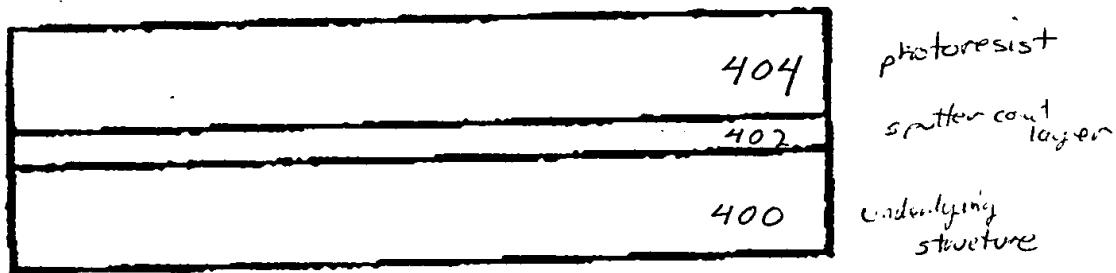


Fig. 4A

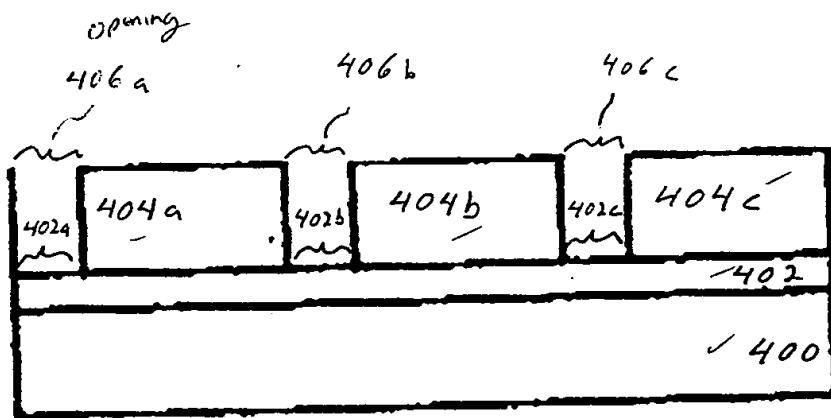


Fig. 4B

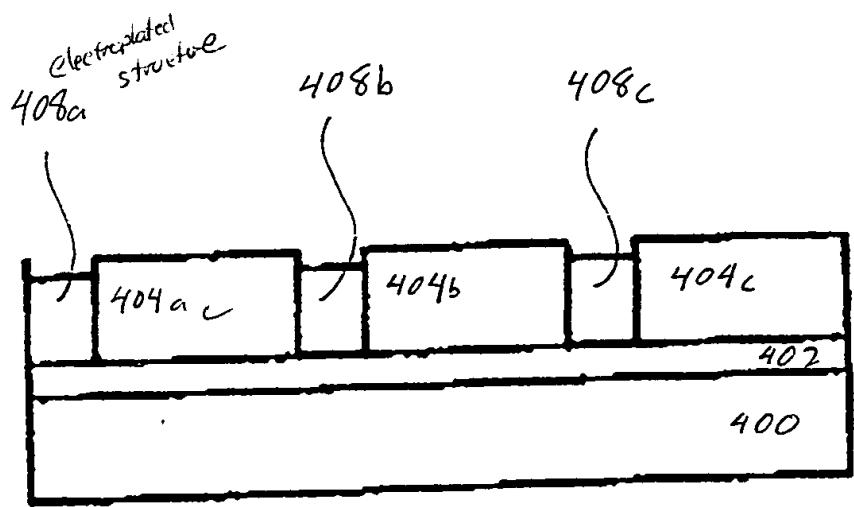


Fig. 4C

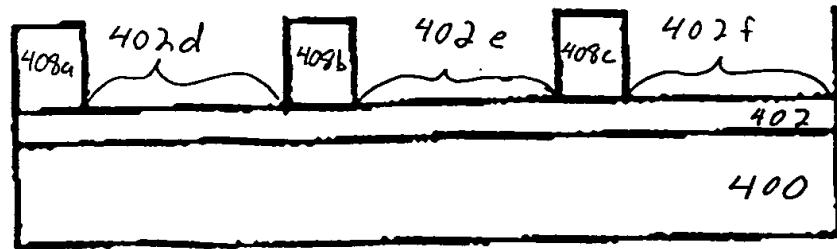


Fig. 4D

OK

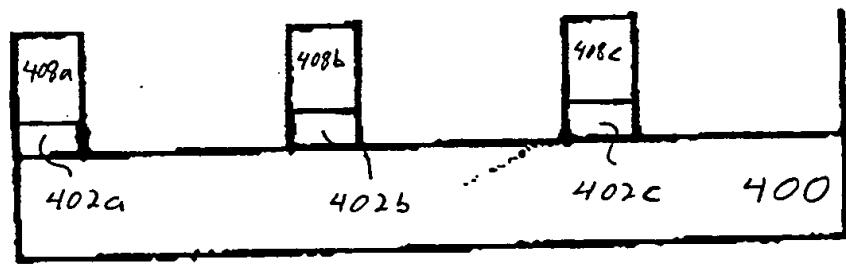


Fig. 4 E

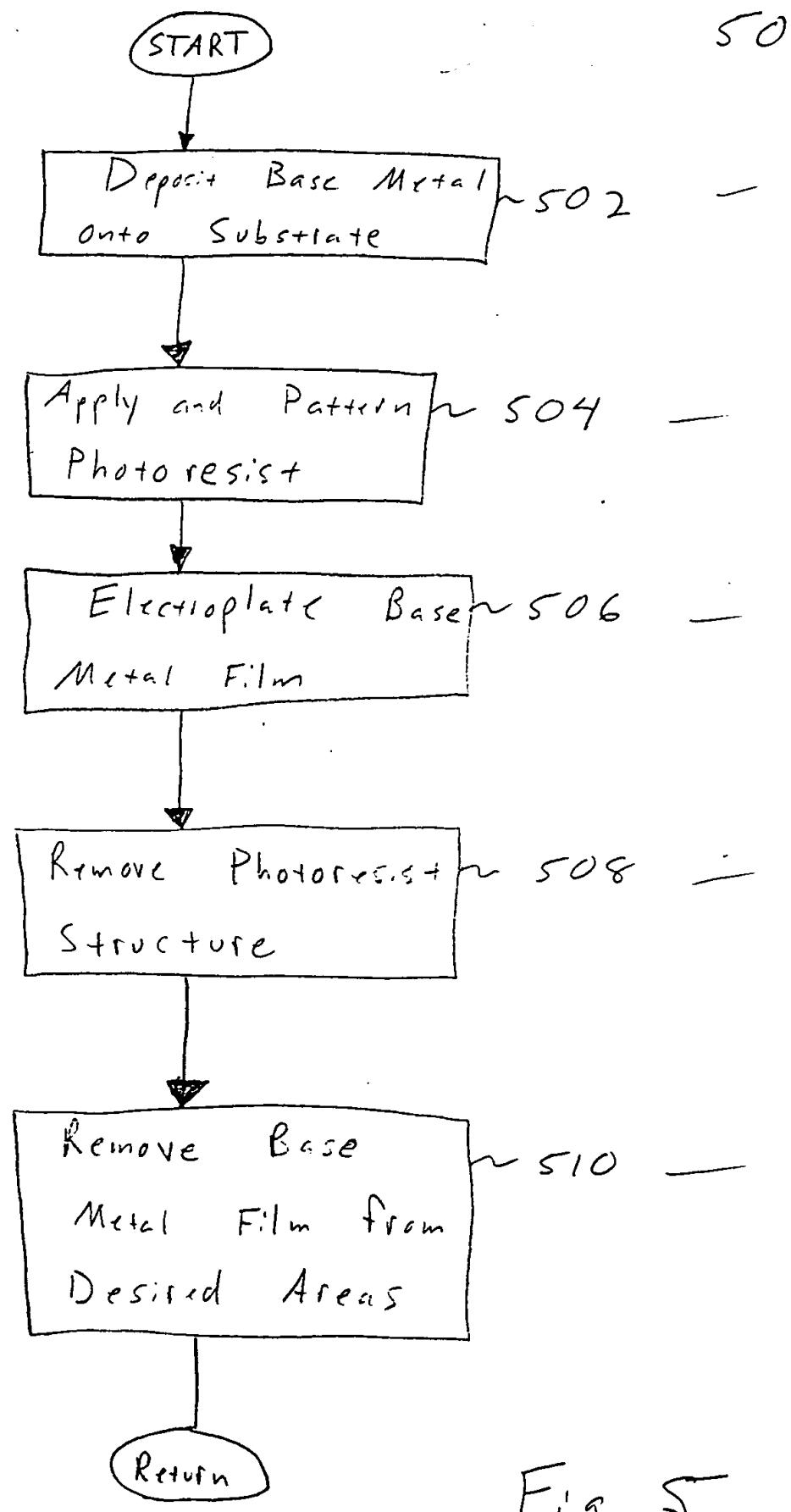


Fig. 5

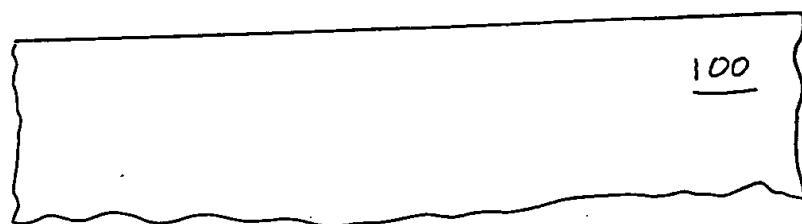


FIG.1A

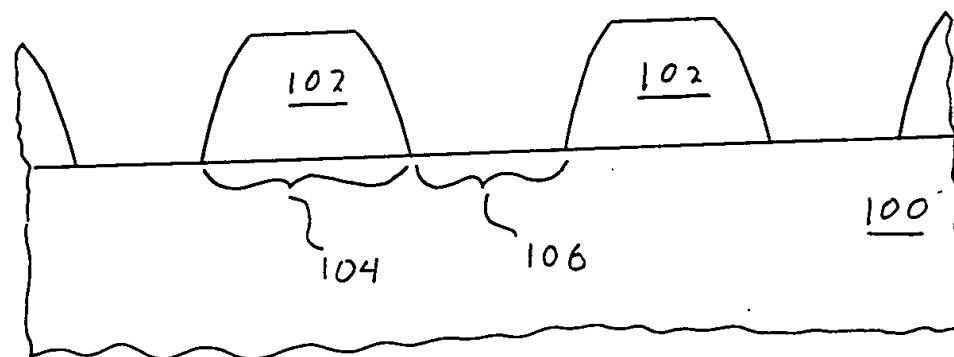


FIG.1B

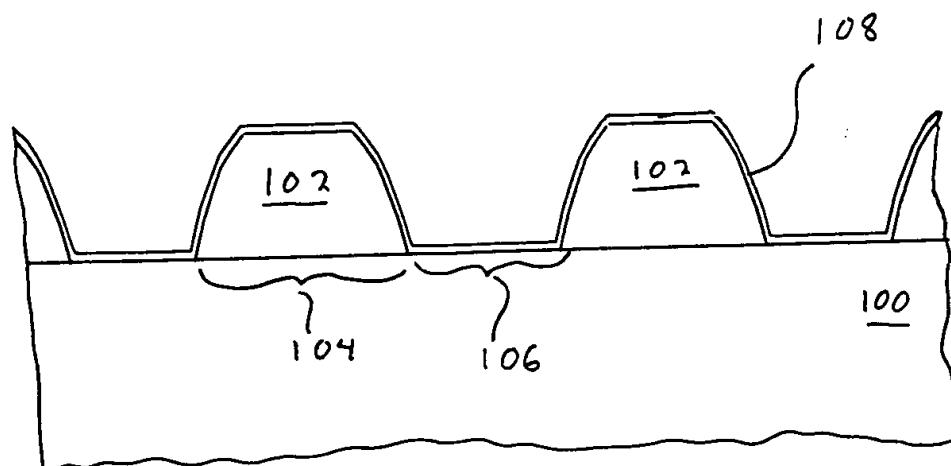
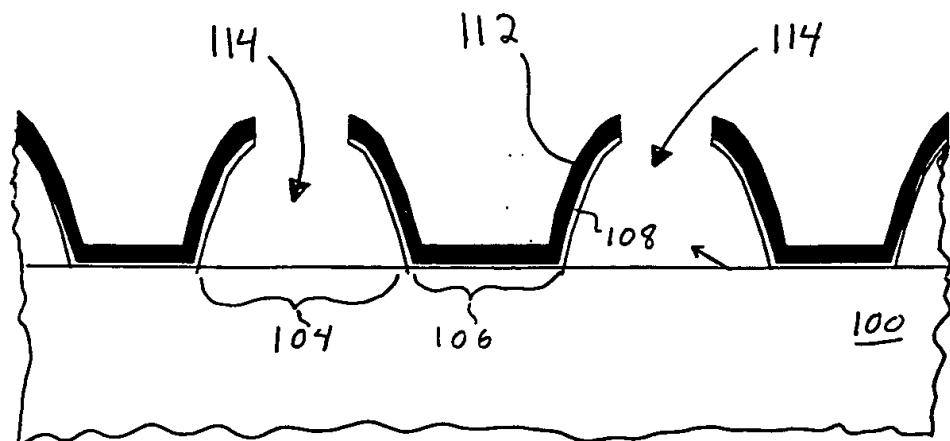
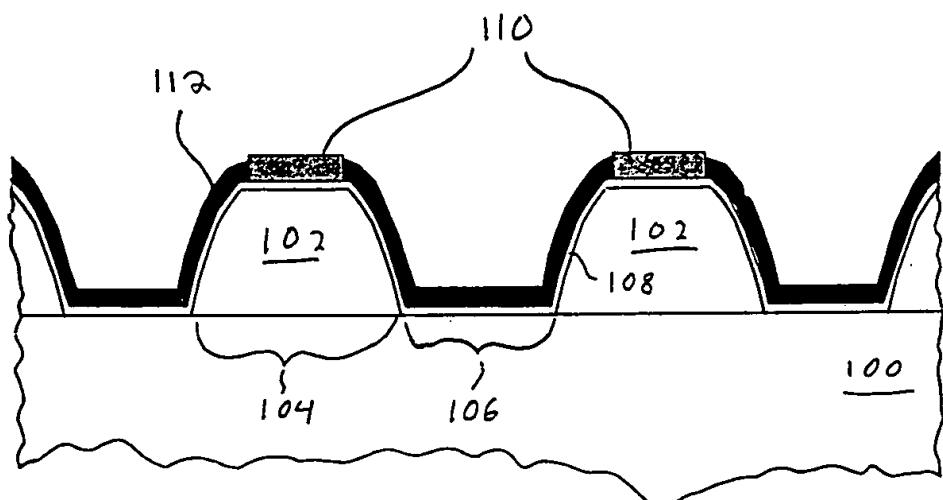
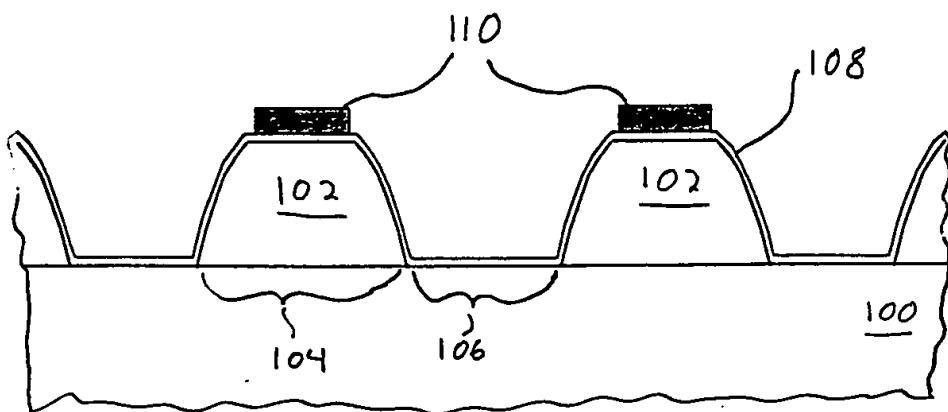


FIG.1C



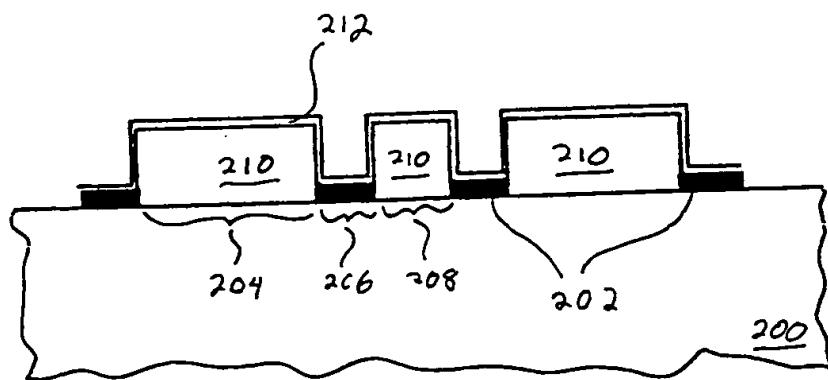
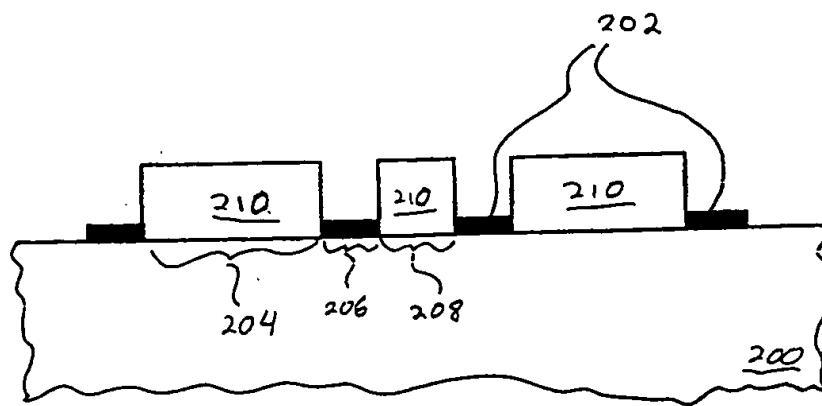
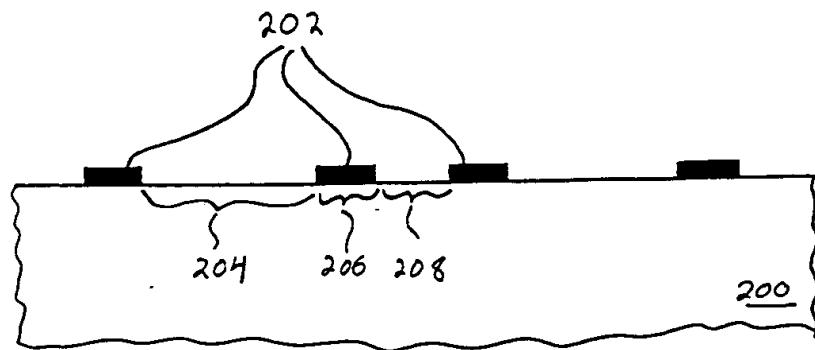


FIG.2D

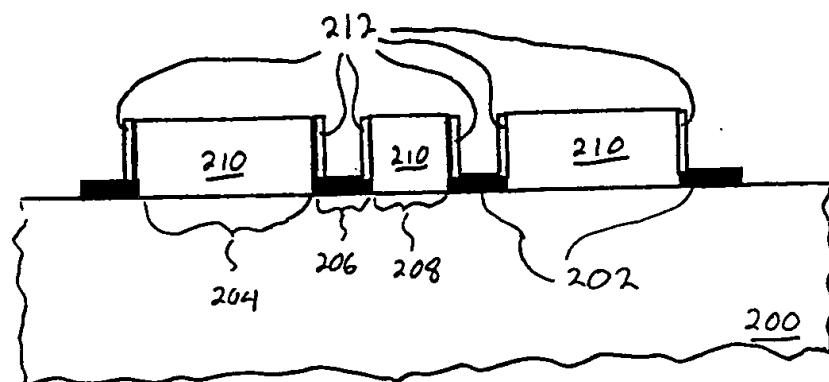


FIG.2E

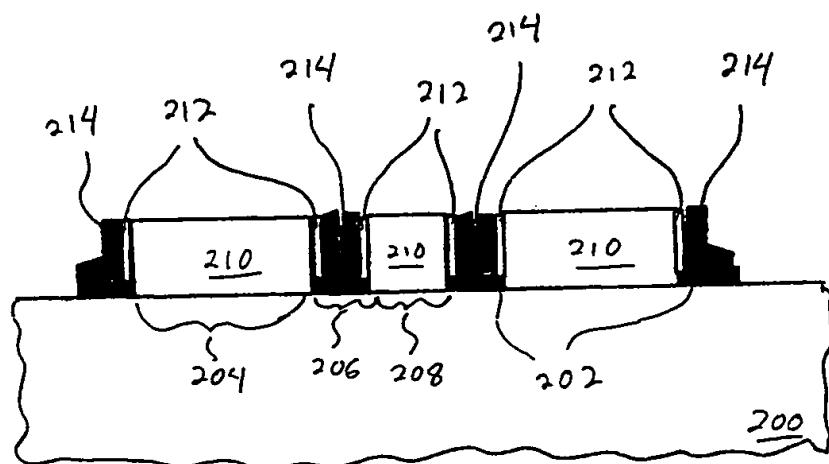


FIG.2F

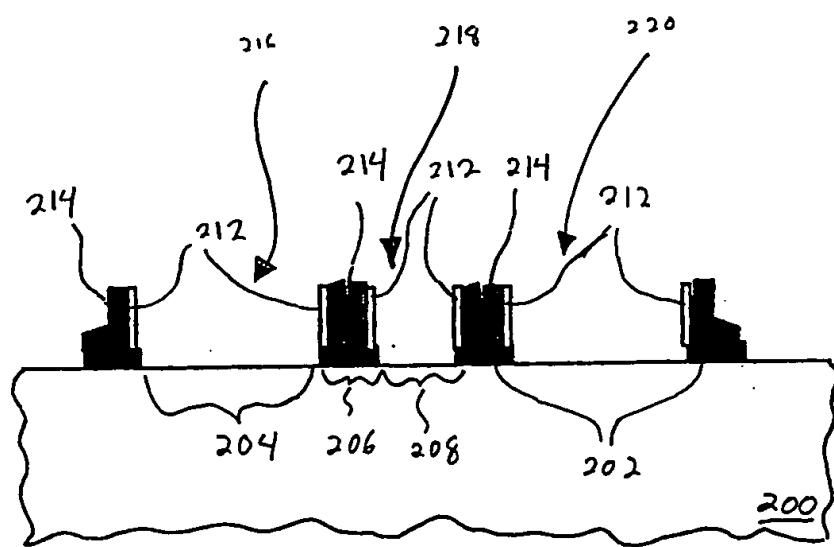
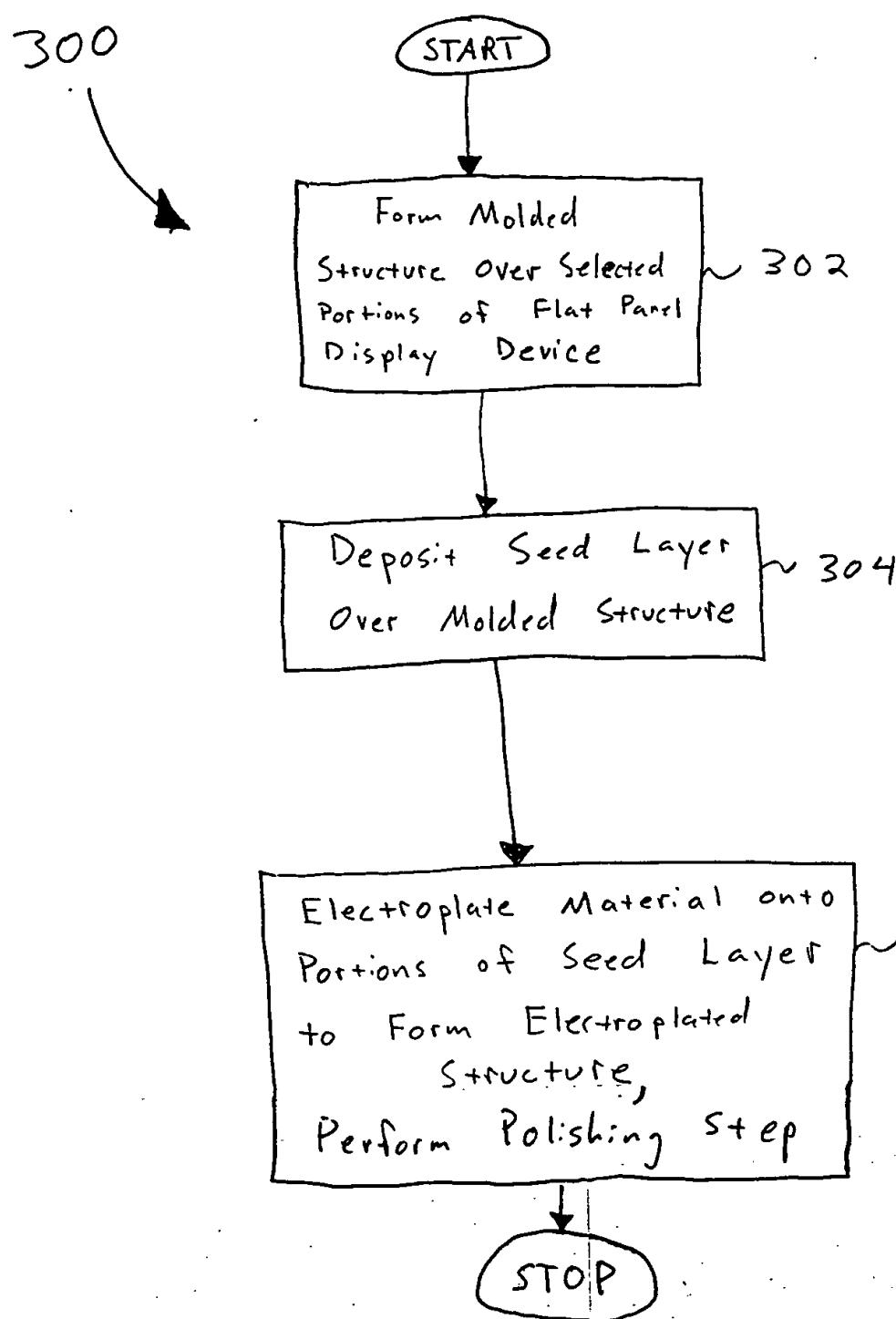


FIG.3



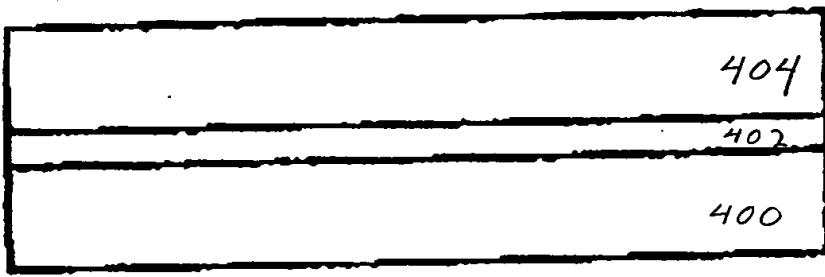


Fig. 4A

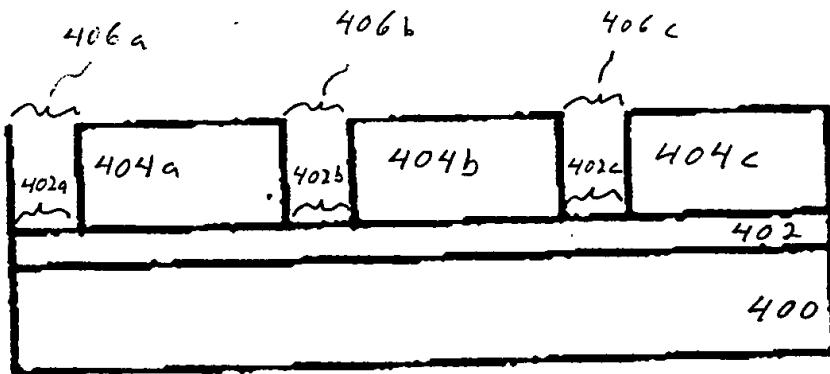


Fig. 4B

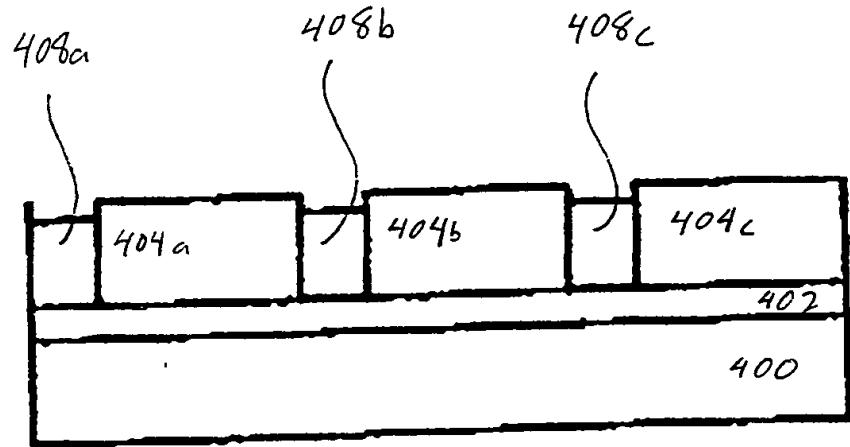


Fig. 4C

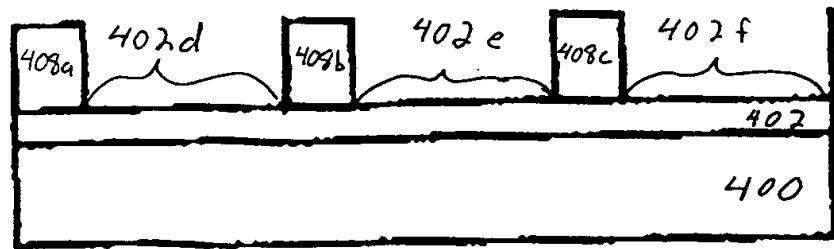


Fig. 4D

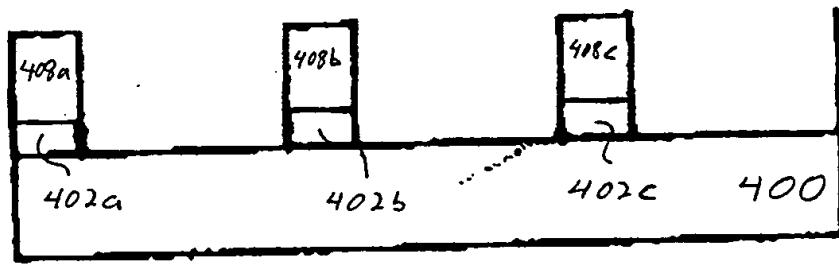


Fig. 4 E

Fig. 5

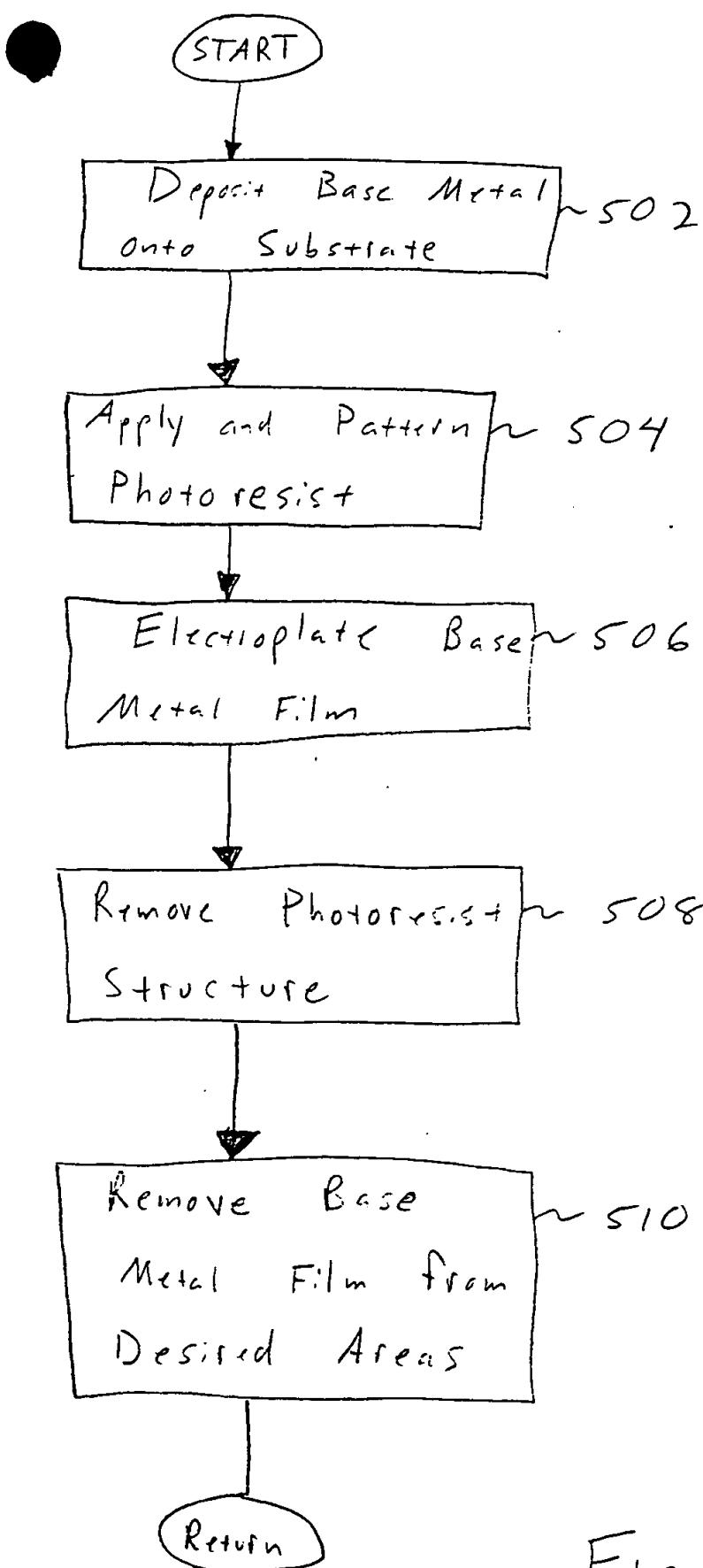


Fig. 5